

# ZXTP19020CFF

## 20V, SOT23F, PNP medium power transistor

### Summary:

$BV_{CEO} > -20V$

$BV_{ECO} > -5V$

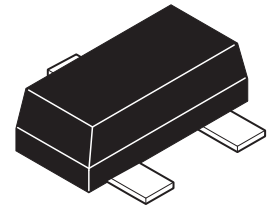
$I_{C(cont)} = -5A$

$V_{CE(sat)} < 40mV @ 100mA$

$R_{CE(sat)} = 21m\Omega$

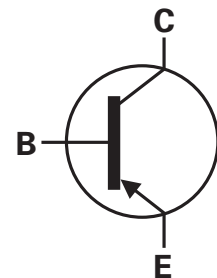
$P_D = 1.5W$

Complementary part number ZXTN19020CFF



### Description

Advanced process capability has been used to maximize the performance of this transistor. The SOT23F package is compatible with the industry standard SOT23 footprint but offers lower profile and higher dissipation for applications where power density is of utmost importance.

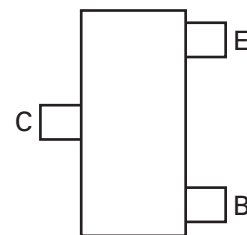


### Features

- High gain
- Low saturation voltage
- Low profile high dissipation package

### Applications

- Battery charging
- Load switch
- DC-DC converters



Pinout - top view

### Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP19020CFFTA	7	8	3000

### Device marking

1D7

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## Absolute maximum ratings

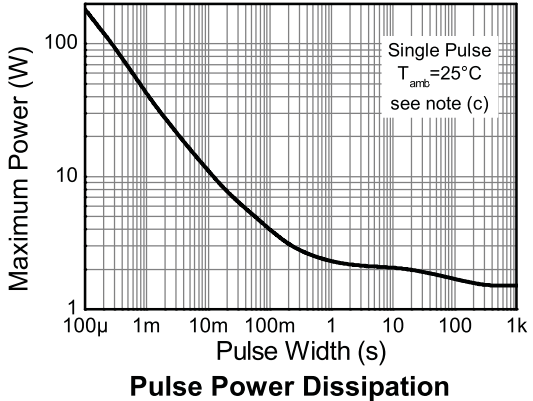
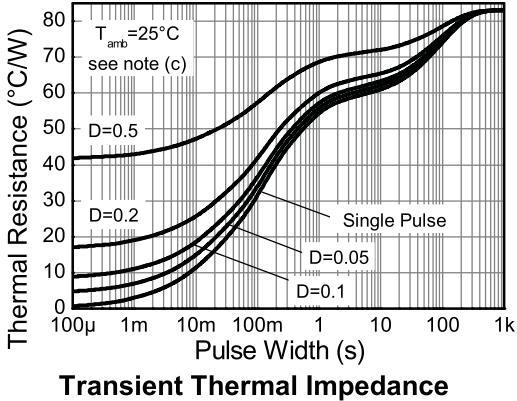
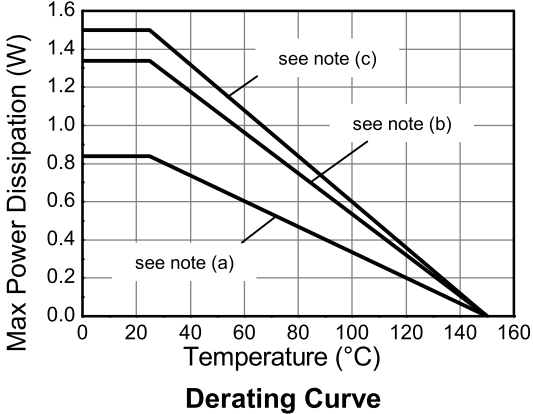
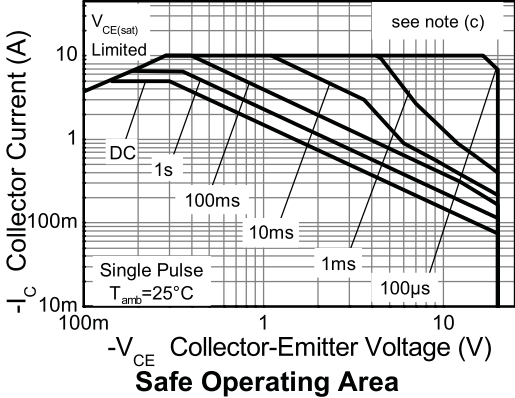
Parameter	Symbol	Limit	Unit
Collector-base voltage	$V_{CBO}$	-25	V
Collector-emitter voltage	$V_{CEO}$	-20	V
Emitter-collector voltage (reverse blocking)	$V_{ECO}$	-5	V
Emitter-base voltage	$V_{EBO}$	-7	V
Continuous collector current <sup>(c)</sup>	$I_C$	-5	A
Peak pulse current	$I_{CM}$	-10	A
Base current	$I_B$	-1	A
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(a)}$	$P_D$	0.84	W
Linear derating factor		6.72	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(b)}$	$P_D$	1.34	W
Linear derating factor		10.72	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(c)}$	$P_D$	1.5	W
Linear derating factor		12.0	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(d)}$	$P_D$	2.0	W
Linear derating factor		16.0	mW/°C
Operating and storage temperature range	$T_j, T_{stg}$	-55 to 150	°C
<b>Thermal resistance</b>			
Parameter	Symbol	Value	Unit
Junction to ambient <sup>(a)</sup>	$R_{\theta JA}$	149.3	°C/W
Junction to ambient <sup>(b)</sup>	$R_{\theta JA}$	93.4	°C/W
Junction to ambient <sup>(c)</sup>	$R_{\theta JA}$	83.3	°C/W
Junction to ambient <sup>(d)</sup>	$R_{\theta JA}$	60	°C/W

### NOTES:

- (a) For a device surface mounted on 15mm x 15mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) Mounted on 25mm x 25mm x 1.6mm FR4 PCB with a high coverage of single sided 2 oz copper in still air conditions.
- (c) Mounted on 50mm x 50mm x 1.6mm FR4 PCB with a high coverage of single sided 2 oz copper in still air conditions.
- (d) As (c) above measured at  $t < 5\text{secs}$ .

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## Characteristics



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## Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

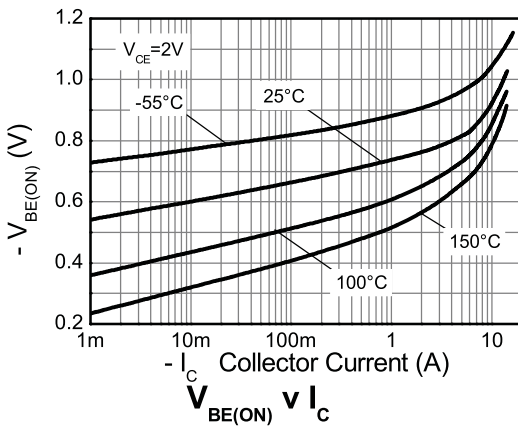
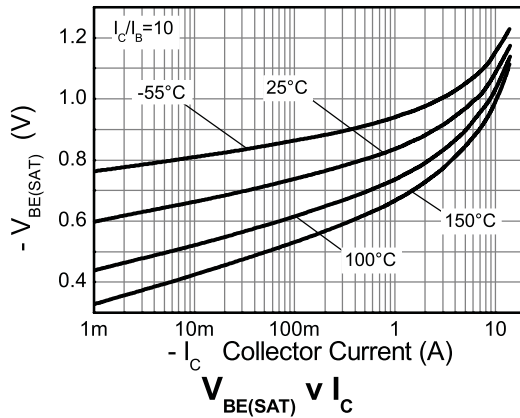
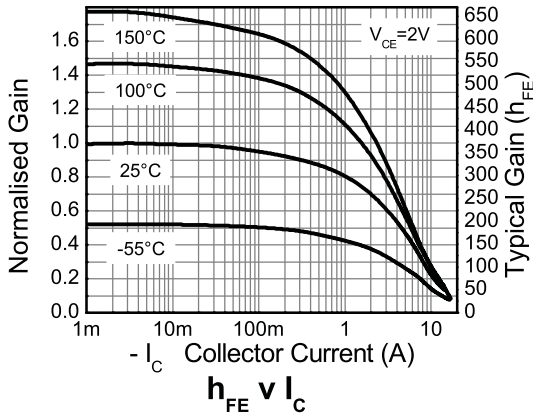
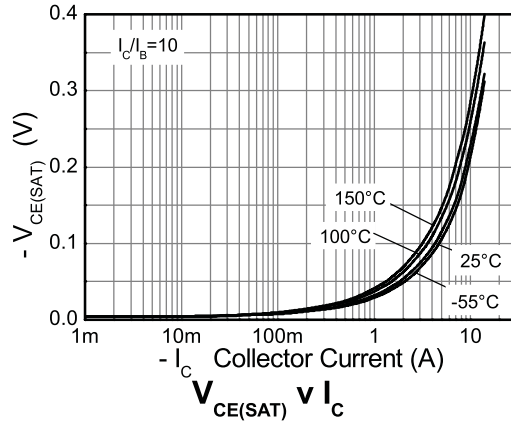
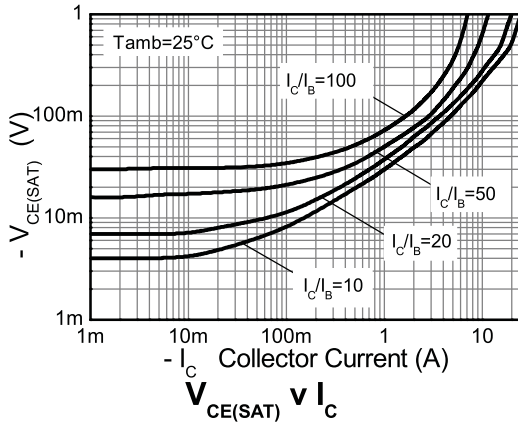
Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-base breakdown voltage	$BV_{CBO}$	-25	-45		V	$I_C = -100\mu\text{A}$
Collector-emitter breakdown voltage (base open)	$BV_{CEO}$	-20	-30		V	$I_C = -10\text{mA}^{(*)}$
Emitter-base breakdown voltage	$BV_{EBO}$	-7	-8.3		V	$I_E = -100\mu\text{A}$
Emitter-collector breakdown voltage (reverse blocking)	$BV_{ECX}$	-6	-8.3		V	$I_E = -100\mu\text{A}$ , $R_{BC} \leq 1\text{k}\Omega$ or $0.25\text{V} < V_{BC} < -0.25\text{V}$
Emitter-collector breakdown voltage (base open)	$BV_{ECO}$	-5	-8.5		V	$I_E = -100\mu\text{A}$ ,
Collector-base cut-off current	$I_{CBO}$		<-1	-50 -20	nA $\mu\text{A}$	$V_{CB} = -20\text{V}$ $V_{CB} = -20\text{V}$ , $T_{amb} = 100^{\circ}\text{C}$
Emitter-base cut-off current	$I_{EBO}$		<-1	-50	nA	$V_{EB} = -5.6\text{V}$
Collector-emitter saturation voltage	$V_{CE(sat)}$		-30 -50 -75 -105	-40 -70 -120 -135	mV mV mV mV	$I_C = -1\text{A}$ , $I_B = -100\text{mA}^{(*)}$ $I_C = -1\text{A}$ , $I_B = -20\text{mA}^{(*)}$ $I_C = -2\text{A}$ , $I_B = -40\text{mA}^{(*)}$ $I_C = -5\text{A}$ , $I_B = -500\text{mA}^{(*)}$
Base-emitter saturation voltage	$V_{BE(sat)}$		-925	-1050	mV	$I_C = -5\text{A}$ , $I_B = -500\text{mA}^{(*)}$
Base-emitter turn-on voltage	$V_{BE(on)}$		-815	-950	mV	$I_C = -5\text{A}$ , $V_{CE} = -2\text{V}^{(*)}$
Static forward current transfer ratio	$h_{FE}$	200 170 110	350 300 180	500		$I_C = -100\text{mA}$ , $V_{CE} = -2\text{V}^{(*)}$ $I_C = -1\text{A}$ , $V_{CE} = -2\text{V}^{(*)}$ $I_C = -5\text{A}$ , $V_{CE} = -2\text{V}^{(*)}$
Transition frequency	$f_T$		200		MHz	$I_C = -50\text{mA}$ , $V_{CE} = -10\text{V}$ $f = 100\text{MHz}$
Output capacitance	$C_{obo}$		52	70	pF	$V_{CB} = -10\text{V}$ , $f = 1\text{MHz}^{(*)}$
Delay time	$t_d$		66.8		ns	$V_{CC} = -15\text{V}$ . $I_C = -750\text{mA}$ , $I_{B1} = 15\text{mA}$ , $I_{B2} = -15\text{mA}$ .
Rise time	$t_r$		74.9		ns	
Storage time	$t_s$		226		ns	
Fall time	$t_f$		85.5		ns	

### NOTES:

(\*) Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

# ZXTP19020CFF

## Typical characteristics

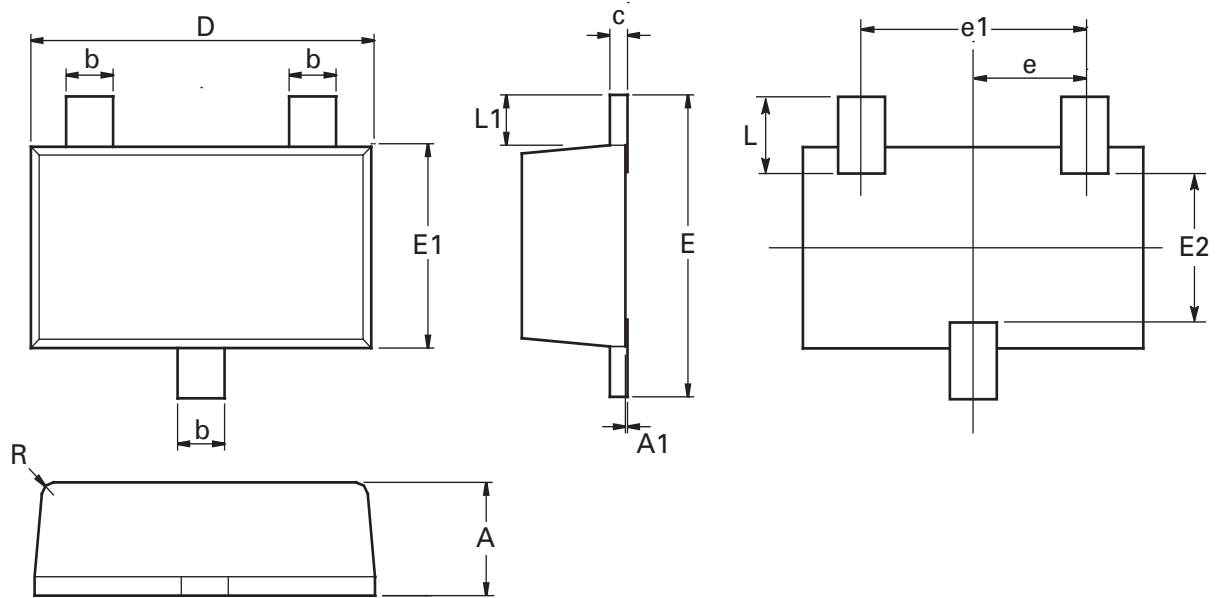


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## Package outline - SOT23F



Dim.	Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Max.	Max.
A	0.80	1.00	0.0315	0.0394	E	2.30	2.50	0.0906	0.0984
A1	0.00	0.10	0.00	0.0043	E1	1.50	1.70	0.0590	0.0669
b	0.35	0.45	0.0153	0.0161	E2	1.10	1.26	0.0433	0.0496
c	0.10	0.20	0.0043	0.0079	L	0.48	0.68	0.0189	0.0268
D	2.80	3.00	0.1102	0.1181	L1	0.30	0.50	0.0153	0.0161
e	0.95 ref		0.0374 ref		R	0.05	0.15	0.0019	0.0059
e1	1.80	2.00	0.0709	0.0787	O	0°	12°	0°	12°

**Note:** Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

# ZXTP19020CFF

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